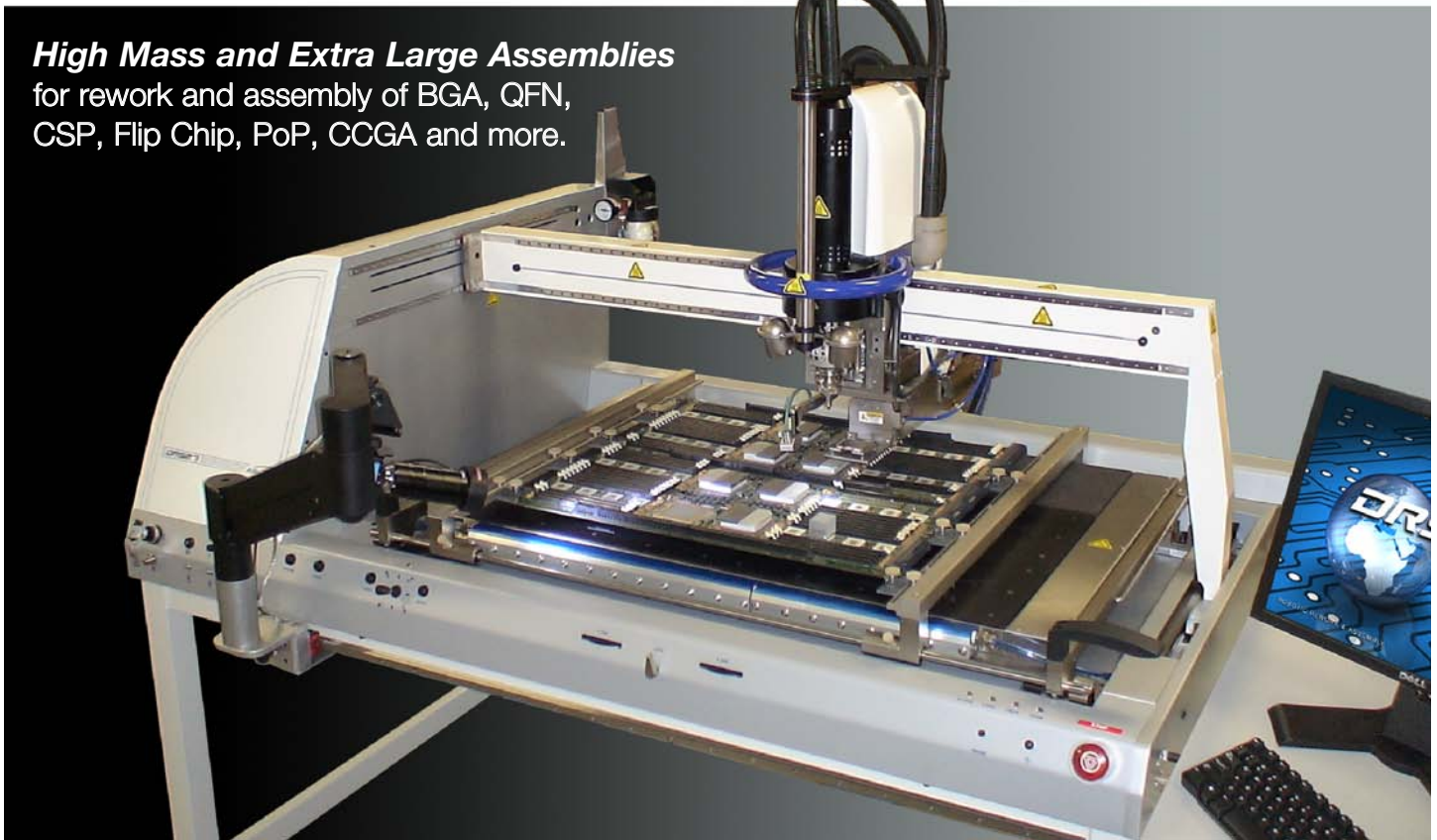


DRS27.6Z

SMT Rework & Repair



High Mass and Extra Large Assemblies
for rework and assembly of BGA, QFN,
CSP, Flip Chip, PoP, CCGA and more.



High Magnification, High Resolution

State-of-the-Art Vision System

Multiple field-of-view camera allows for extremely close-up viewing of all four corners plus center area of part/location for precision alignment.

Consistent, Precision Vision Alignment

Moveable X/Y Head and Fixed Board Locations

Assemblies remain at a fixed position in the carrier while the overhead robotic head picks, aligns and places components with an 18 micron placement accuracy.

Automatic Component Pick and Place

Motorized Z-Axis & Theta Rotation

Control motion via front mounted joystick control. Programmable component pick-up and adjustable force placement (grams).

Enhanced Force Placement

Load Cells Measure 20-2000 Grams

Programmable Cool Down

Integrated Board Cooling System

Built into the carrier, upper cool air injection bypasses heating element and air flows directly into nozzle (component).

Extra Large Carrier

Preheaters for Large Assemblies

Standard 6-zone preheater, 32" x 24", 15,000 watts.

Excellent Thermal Uniformity

High Efficiency IR Preheater

- Insulated heating elements provide ultra-fast heat up (+/- 5 degrees C).
- Black ceramic, high-emissivity coating dramatically increases radiant energy to produce the significantly higher preheat temperatures required for lead-free rework.
- Excellent for high thermal mass, military type assemblies (metal frames).

Flexible Bottom-Side Clearance

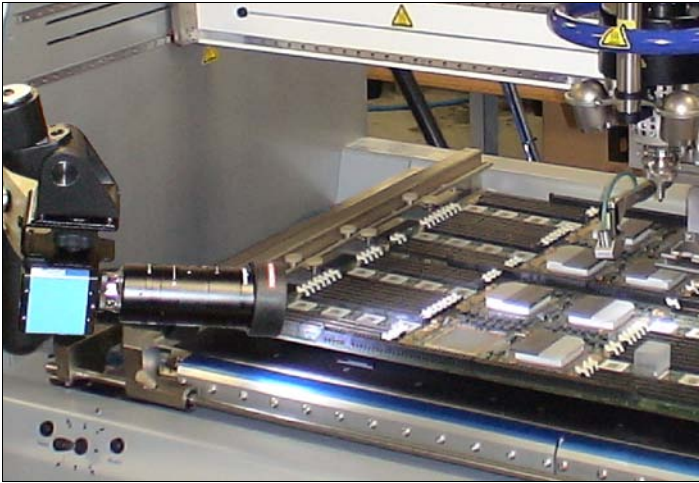
User Adjustable

Keep close for better performance - move away for up to 1.62" bottom-side clearance.

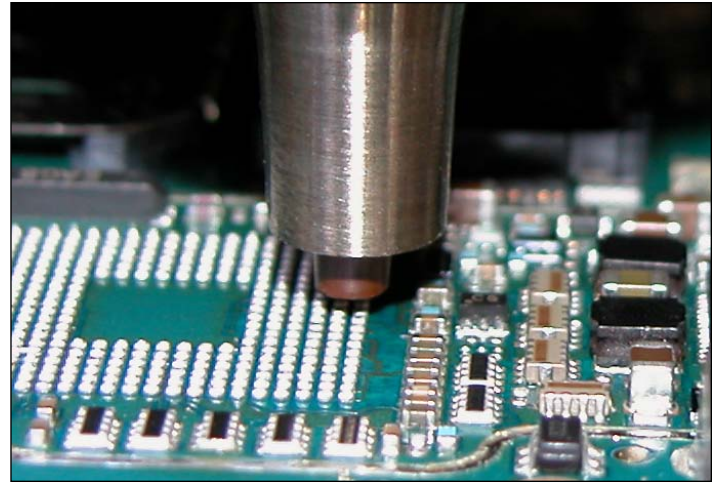
User-Friendly Software

8 Thermocouple Channels

Profile assemblies with Thermal Tutor Software. "On the fly" temperature and air flow adjustments are standard. Profile library and master thermal templates are part of the software package.



SIDE VIEW CAMERA



STANDARD & MICRO SITE CLEANING

DRS27.6Z Standard Systems Include:

- 6-Zone, High Efficiency 32" x 24" IR Preheater (15,000 watts total)
- Programmable Board Cooling System (Air-Knife)
- 2000 Watt Top Heater
- Cool-Air Injection (Nozzle)
- Motorized Z axis and Theta control
- Multiple Field of View Vision with Top/Bottom LED Lighting, (x and y motor drives)
- 70 mm maximum component size
- Board Carrier Size 32"W x 24"D
- Joystick operation for all motor controls
- 8 Thermocouple Channels
- Welded Steel Frame with Side Table
- Adjustable LED Lighting for PCB
- Thermal Tutor Software
- DELL PC/ Flat Screen Monitor/Keyboard/Mouse
- Tool Kit & Board Supports

Specifications:

- Machine Dimensions: 86"W x 48"D x 66"H
- Machine Weight: 450 lbs. (204 kgs)
- Maximum Board Size: 32"W x 24"D (812 x 609mm)
- Facility Requirements: 208-220 volts, 50 amps, 3 Phase

Recommended Options:

- **Pivoting IR Sensor w/Laser Pointer** (0029.11.041)
Provides process repeatability by insuring that the board is at the exact same target temperature each time
- **Site Cleaning System** (0029.03.012)
Includes standard and micro nozzles for complete removal of site solder.
- **Universal Insertion Tool** (AU6LGA47R)
Mechanically self-centers any device for accurate pick up.
- **Direct View Camera** (0027.15.012)
Provides high magnification site viewing.
- **Dipping Kit for Solder Paste or Flux** (FASET1)
Superior to applying paste via component or board stencils.
- **70mm Topside Clearance** (Std is 30mm) (0029.01.052)
- **Fume Extraction Manifold** (300.00.547)
- **Air Purification Unit** (1020.01.105)
- **Paste-On-Device Stencil Adapter** (0024.24.111)
- **4 Additional Thermocouple Ports** (300.00.504)
- **Colored LED Lighting**